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09/594502
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Class	Subclass	ISSUE CLASSIFICATION

C

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/594502	F	451	41	3723	Rose

APPLICANTS: Tomohiro Hashii

TITLE: Semiconductor wafer grinding method

PTO-2040
12/99

ISSUING CLASSIFICATION

ORIGINAL		CROSS REFERENCE(S)					
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)				
INTERNATIONAL CLASSIFICATION							

☐ Continued on Issue Slip Inside File Jacket

☐ TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.

☐ The term of this patent subsequent to ____________ (date) has been disclaimed.

☐ The term of this patent shall not extend beyond the expiration date of U.S Patent. No. ____________

☐ The terminal ____ months of this patent have been disclaimed.

____________ (Assistant Examiner) ______ (Date)

____________ (Primary Examiner) ______ (Date)

____________ (Legal Instruments Examiner) ______ (Date)

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due	Date Paid

ISSUE BATCH NUMBER

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